DZ2U200

Silicon epitaxial planar type

For constant voltage / waveform clipper and surge absorption circuit
Low noise type
DZ27200 in USSMini2 type package

■ Features

- Excellent rising characteristics of zener current I_Z
- Low zener operating resistance R_Z
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Packaging

Embossed type (Thermo-compression sealing): 10000 pcs / reel (standard)

■ Package

- Code
  USSMini2-F2-B
- Pin Name
  1. Cathode
  2. Anode

■ Marking Symbol: Z

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	I_{FRM}	200	mA
Total power dissipation *	P_T	120	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	–55 to +150	°C

Note) *: P_T = 120 mW achieved with a printed circuit board.

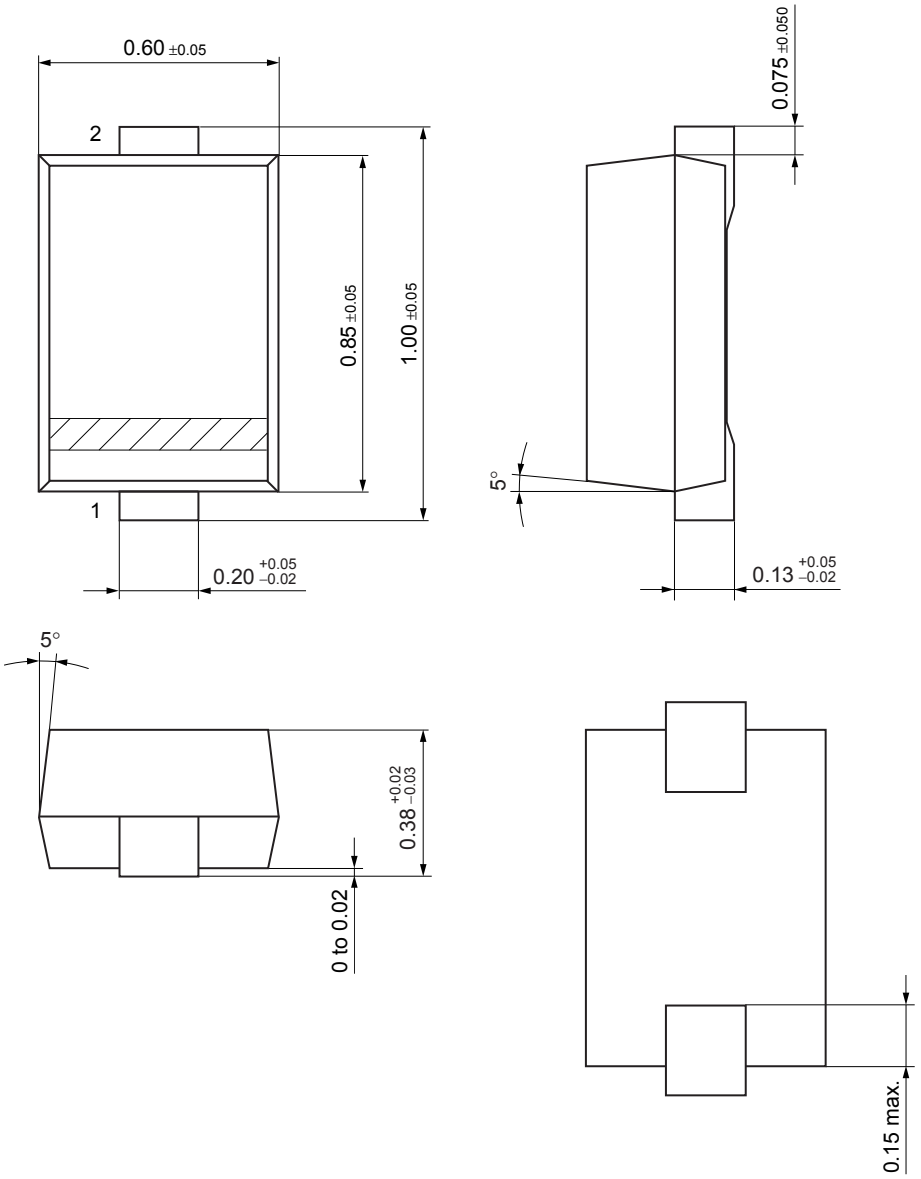
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 10 mA			1.0	V
Zener voltage *1, 2	V_Z	I_Z = 5 mA	19.00		21.00	V
Zener operating resistance	R_Z	I_Z = 5 mA			80	Ω
Reverse current	I_R	V_R = 15 V			0.05	μA
Temperature coefficient of zener voltage *3	S_Z	I_Z = 5 mA		18.4		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 5 MHz.
3. *1: The temperature must be controlled 25°C for V_Z measurement. V_Z value measured at other temperature must be adjusted to V_Z (25°C)
*2: V_Z guaranteed 20 ms after current flow.
*3: T_j = 25°C to 150°C

USSMini2-F2-B

Unit: mm



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